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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

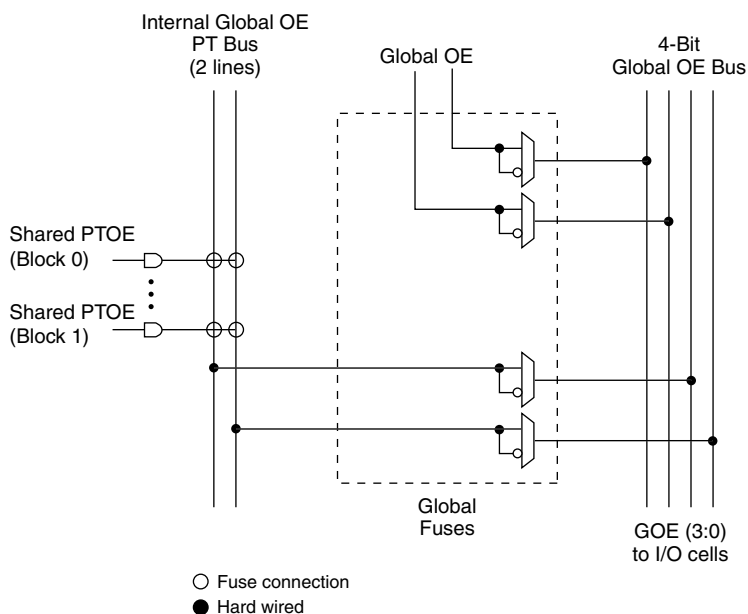
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	-
Number of I/O	128
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	176-LQFP
Supplier Device Package	176-TQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4256v-75t176c

Figure 2. Generic Logic Block

AND Array

The programmable AND Array consists of 36 inputs and 83 output product terms. The 36 inputs from the GRP are used to form 72 lines in the AND Array (true and complement of the inputs). Each line in the array can be connected to any of the 83 output product terms via a wired-AND. Each of the 80 logic product terms feed the logic allocator with the remaining three control product terms feeding the Shared PT Clock, Shared PT Initialization and Shared PT OE. The Shared PT Clock and Shared PT Initialization signals can optionally be inverted before being fed to the macrocells.

Every set of five product terms from the 80 logic product terms forms a product term cluster starting with PT0. There is one product term cluster for every macrocell in the GLB. Figure 3 is a graphical representation of the AND Array.

Figure 10. Global OE Generation for ispMACH 4032

Zero Power/Low Power and Power Management

The ispMACH 4000 family is designed with high speed low power design techniques to offer both high speed and low power. With an advanced E^2 low power cell and non sense-amplifier design approach (full CMOS logic approach), the ispMACH 4000 family offers SuperFAST pin-to-pin speeds, while simultaneously delivering low standby power without needing any “turbo bits” or other power management schemes associated with a traditional sense-amplifier approach.

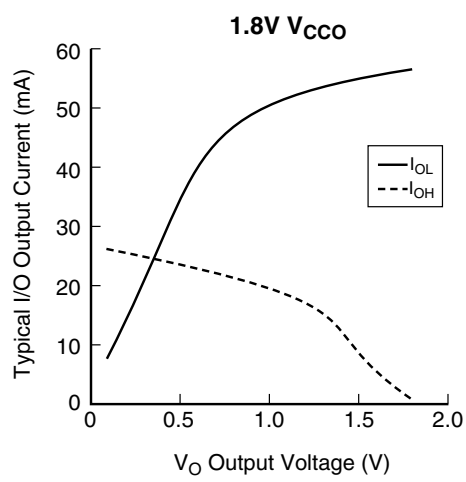
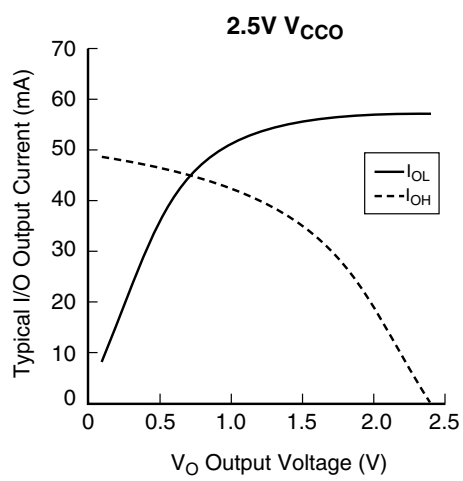
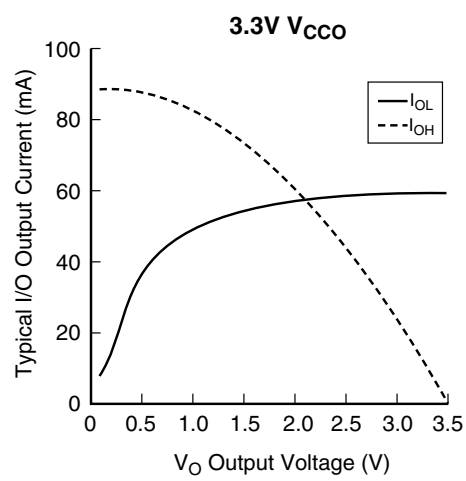
The zero power ispMACH 4000Z is based on the 1.8V ispMACH 4000C family. With innovative circuit design changes, the ispMACH 4000Z family is able to achieve the industry’s “lowest static power”.

IEEE 1149.1-Compliant Boundary Scan Testability

All ispMACH 4000 devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more board-level testing. The test access port operates with an LVCMOS interface that corresponds to the power supply voltage.

I/O Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os’ physical nature should be minimal so that board test time is minimized. The ispMACH 4000 family of devices allows this by offering the user the ability to quickly configure the physical nature of the I/O cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice’s ispVM® System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.



ispMACH 4000V/B/C External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description ^{1, 2, 3}	-25		-27		-3		-35		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	5-PT bypass combinatorial propagation delay	—	2.5	—	2.7	—	3.0	—	3.5	ns
t _{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	3.2	—	3.5	—	3.8	—	4.2	ns
t _S	GLB register setup time before clock	1.8	—	1.8	—	2.0	—	2.0	—	ns
t _{ST}	GLB register setup time before clock with T-type register	2.0	—	2.0	—	2.2	—	2.2	—	ns
t _{SIR}	GLB register setup time before clock, input register path	0.7	—	1.0	—	1.0	—	1.0	—	ns
t _{SIRZ}	GLB register setup time before clock with zero hold	1.7	—	2.0	—	2.0	—	2.0	—	ns
t _H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time after clock, input register path	0.9	—	1.0	—	1.0	—	1.0	—	ns
t _{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	2.2	—	2.7	—	2.7	—	2.7	ns
t _R	External reset pin to output delay	—	3.5	—	4.0	—	4.4	—	4.5	ns
t _{RW}	External reset pulse duration	1.5	—	1.5	—	1.5	—	1.5	-	ns
t _{PTOE/DIS}	Input to output local product term output enable/disable	—	4.0	—	4.5	—	5.0	—	5.5	ns
t _{GPTOE/DIS}	Input to output global product term output enable/disable	—	5.0	—	6.5	—	8.0	—	8.0	ns
t _{GOE/DIS}	Global OE input to output enable/disable	—	3.0	—	3.5	—	4.0	—	4.5	ns
t _{CW}	Global clock width, high or low	1.1	—	1.3	—	1.3	—	1.3	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.1	—	1.3	—	1.3	—	1.3	—	ns
t _{WIR}	Input register clock width, high or low	1.1	—	1.3	—	1.3	—	1.3	—	ns
f _{MAX} ⁴	Clock frequency with internal feedback	—	400	—	333	—	322	—	322	MHz
f _{MAX} (Ext.)	Clock frequency with external feedback, [1/ (t _S + t _{CO})]	—	250	—	222	—	212	—	212	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.3.2

2. Measured using standard switching circuit, assuming GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

ispMACH 4000Z External Switching Characteristics (Cont.)**Over Recommended Operating Conditions**

Parameter	Description ^{1, 2, 3}	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	5-PT bypass combinatorial propagation delay	—	4.5	—	5.0	—	7.5	ns
t _{PD_MC}	20-PT combinatorial propagation delay through macrocell	—	5.8	—	6.0	—	8.0	ns
t _S	GLB register setup time before clock	2.9	—	3.0	—	4.5	—	ns
t _{ST}	GLB register setup time before clock with T-type register	3.1	—	3.2	—	4.7	—	ns
t _{SIR}	GLB register setup time before clock, input register path	1.3	—	1.3	—	1.4	—	ns
t _{SIRZ}	GLB register setup time before clock with zero hold	2.6	—	2.6	—	2.7	—	ns
t _H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t _{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time after clock, input register path	1.3	—	1.3	—	1.3	—	ns
t _{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	3.8	—	4.2	—	4.5	ns
t _R	External reset pin to output delay	—	7.5	—	7.5	—	9.0	ns
t _{RW}	External reset pulse duration	2.0	—	2.0	—	4.0	—	ns
t _{PTOE/DIS}	Input to output local product term output enable/disable	—	8.2	—	8.5	—	9.0	ns
t _{GPTOE/DIS}	Input to output global product term output enable/disable	—	10.0	—	10.0	—	10.5	ns
t _{GOE/DIS}	Global OE input to output enable/disable	—	5.5	—	6.0	—	7.0	ns
t _{CW}	Global clock width, high or low	1.8	—	2.0	—	2.8	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.8	—	2.0	—	2.8	—	ns
t _{WIR}	Input register clock width, high or low	1.8	—	2.0	—	2.8	—	ns
f _{MAX} ⁴	Clock frequency with internal feedback	—	200	—	200	—	168	MHz
f _{MAX} (Ext.)	clock frequency with external feedback, [1 / (t _S + t _{CO})]	—	150	—	139	—	111	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.2.2

2. Measured using standard switching GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

ispMACH 4000V/B/C Internal Timing Parameters (Cont.)**Over Recommended Operating Conditions**

Parameter	Description	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{GPTOE}	Global PT OE Delay	—	5.58	—	5.58	—	5.78	ns
t _{PTOE}	Macrocell PT OE Delay	—	3.58	—	4.28	—	4.28	ns

Timing v.3.2

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the Timing Model in this data sheet for further details.

ispMACH 4000Z Internal Timing Parameters (Cont.)**Over Recommended Operating Conditions**

Parameter	Description	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays								
t _{IN}	Input Buffer Delay	—	0.95	—	1.25	—	1.80	ns
t _{GOE}	Global OE Pin Delay	—	3.00	—	3.50	—	4.30	ns
t _{GCLK_IN}	Global Clock Input Buffer Delay	—	1.95	—	2.05	—	2.15	ns
t _{BUF}	Delay through Output Buffer	—	1.10	—	1.00	—	1.30	ns
t _{EN}	Output Enable Time	—	2.50	—	2.50	—	2.70	ns
t _{DIS}	Output Disable Time	—	2.50	—	2.50	—	2.70	ns
Routing/GLB Delays								
t _{ROUTE}	Delay through GRP	—	2.25	—	2.05	—	2.50	ns
t _{MCELL}	Macrocell Delay	—	0.65	—	0.65	—	1.00	ns
t _{INREG}	Input Buffer to Macrocell Register Delay	—	1.00	—	1.00	—	1.00	ns
t _{FBK}	Internal Feedback Delay	—	0.35	—	0.05	—	0.05	ns
t _{PDb}	5-PT Bypass Propagation Delay	—	0.20	—	0.70	—	1.90	ns
t _{PDi}	Macrocell Propagation Delay	—	0.45	—	0.65	—	1.00	ns
Register/Latch Delays								
t _S	D-Register Setup Time (Global Clock)	1.00	—	1.10	—	1.35	—	ns
t _{S_PT}	D-Register Setup Time (Product Term Clock)	2.10	—	1.90	—	2.45	—	ns
t _{ST}	T-Register Setup Time (Global Clock)	1.20	—	1.30	—	1.55	—	ns
t _{ST_PT}	T-register Setup Time (Product Term Clock)	2.30	—	2.10	—	2.75	—	ns
t _H	D-Register Hold Time	1.90	—	1.90	—	3.15	—	ns
t _{HT}	T-Resister Hold Time	1.90	—	1.90	—	3.15	—	ns
t _{SIR}	D-Input Register Setup Time (Global Clock)	1.30	—	1.10	—	0.75	—	ns
t _{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
t _{HIR}	D-Input Register Hold Time (Global Clock)	1.30	—	1.50	—	1.95	—	ns
t _{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	1.00	—	1.00	—	1.18	—	ns
t _{COi}	Register Clock to Output/Feedback MUX Time	—	0.75	—	1.15	—	1.05	ns
t _{CES}	Clock Enable Setup Time	2.00	—	2.00	—	2.00	—	ns
t _{CEH}	Clock Enable Hold Time	0.00	—	0.00	—	0.00	—	ns
t _{SL}	Latch Setup Time (Global Clock)	1.00	—	1.00	—	1.65	—	ns
t _{SL_PT}	Latch Setup Time (Product Term Clock)	2.10	—	1.90	—	2.15	—	ns
t _{HL}	Latch Hold Time	2.00	—	2.00	—	1.17	—	ns
t _{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—	0.33	ns
t _{PDLi}	Propagation Delay through Transparent Latch to Output/ Feedback MUX	—	0.25	—	0.25	—	0.25	ns
t _{SRi}	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.97	—	0.97	—	0.28	ns
t _{SRR}	Asynchronous Reset or Set Recovery Delay	—	1.80	—	1.80	—	1.67	ns
Control Delays								
t _{BCLK}	GLB PT Clock Delay	—	1.55	—	1.55	—	1.25	ns
t _{PTCLK}	Macrocell PT Clock Delay	—	1.55	—	1.55	—	1.25	ns
t _{BSR}	GLB PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	ns
t _{PTSR}	Macrocell PT Set/Reset Delay	—	1.83	—	1.83	—	2.72	ns
t _{GPTOE}	Global PT OE Delay	—	4.30	—	4.20	—	3.50	ns

ispMACH 4000Z Timing Adders (Cont.)¹

Adder Type	Base Parameter	Description	-45		-5		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Optional Delay Adders									
t _{INDIO}	t _{INREG}	Input register delay	—	1.30	—	1.30	—	1.30	ns
t _{EXP}	t _{MCELL}	Product term expander delay	—	0.45	—	0.45	—	0.50	ns
t _{ORP}	—	Output routing pool delay	—	0.40	—	0.40	—	0.40	ns
t _{BLA}	t _{ROUTE}	Additional block load-ing adder	—	0.05	—	0.05	—	0.05	ns
t _{IOI} Input Adjusters									
LVTTTL_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVTTTL standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS33_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS25_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS18_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVC MOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
t _{IOO} Output Adjusters									
LVTTTL_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS33_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS25_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVC MOS18_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t _{BUF} , t _{EN}	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

Timing v.2.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

Boundary Scan Waveforms and Timing Specifications

Symbol	Parameter	Min.	Max.	Units
t_{BTCP}	TCK [BSCAN test] clock cycle	40	—	ns
t_{BTCH}	TCK [BSCAN test] pulse width high	20	—	ns
t_{BTCL}	TCK [BSCAN test] pulse width low	20	—	ns
t_{BTSU}	TCK [BSCAN test] setup time	8	—	ns
t_{BTH}	TCK [BSCAN test] hold time	10	—	ns
t_{BRF}	TCK [BSCAN test] rise and fall time	50	—	mV/ns
t_{BTCO}	TAP controller falling edge of clock to valid output	—	10	ns
t_{BTOZ}	TAP controller falling edge of clock to data output disable	—	10	ns
t_{BTVO}	TAP controller falling edge of clock to data output enable	—	10	ns
t_{BTCPSU}	BSCAN test Capture register setup time	8	—	ns
t_{BTCPH}	BSCAN test Capture register hold time	10	—	ns
t_{BTUCO}	BSCAN test Update reg, falling edge of clock to valid output	—	25	ns
t_{BTUOZ}	BSCAN test Update reg, falling edge of clock to output disable	—	25	ns
t_{BTUOV}	BSCAN test Update reg, falling edge of clock to output enable	—	25	ns

Signal Descriptions

Signal Names	Description
TMS	Input – This pin is the IEEE 1149.1 Test Mode Select input, which is used to control the state machine.
TCK	Input – This pin is the IEEE 1149.1 Test Clock input pin, used to clock through the state machine.
TDI	Input – This pin is the IEEE 1149.1 Test Data In pin, used to load data.
TDO	Output – This pin is the IEEE 1149.1 Test Data Out pin used to shift data out.
GOE0/IO, GOE1/IO	These pins are configured to be either Global Output Enable Input or as general I/O pins.
GND	Ground
NC	Not Connected
V _{CC}	The power supply pins for logic core and JTAG port.
CLK0/I, CLK1/I, CLK2/I, CLK3/I	These pins are configured to be either CLK input or as an input.
V _{CC00} , V _{CC01}	The power supply pins for each I/O bank.
yzz	Input/Output ¹ – These are the general purpose I/O used by the logic array. y is GLB reference (alpha) and z is macrocell reference (numeric). z: 0-15.
	ispMACH 4032 y: A-B
	ispMACH 4064 y: A-D
	ispMACH 4128 y: A-H
	ispMACH 4256 y: A-P
	ispMACH 4384 y: A-P, AX-HX
	ispMACH 4512 y: A-P, AX-PX

1. In some packages, certain I/Os are only available for use as inputs. See the signal connections table for details.

ispMACH 4000V/B/C ORP Reference Table

	4032V/B/C		4064V/B/C			4128V/B/C			4256V/B/C				4384V/B/C		4512V/B/C	
Number of I/Os	30 ¹	32	30 ²	32	64	64	92 ³	96	64	96 ⁴	128	160	128	192	128	208
Number of GLBs	2	2	4	4	4	8	8	8	16	16	16	16	16	16	16	16
Number of I/Os / GLB	16	16	8	8	16	8	12	12	4	8	8	10	8	8	8	Mixture of 8 & 4 ⁵
Reference ORP Table	16 I/Os / GLB		8 I/Os / GLB		16 I/Os / GLB	8 I/Os / GLB	12 I/Os / GLB		4 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB	10 I/Os / GLB	8 I/Os / GLB		8 I/Os / GLB	8 I/Os / GLB 4 I/Os / GLB

1. 32-macrocell device, 44 TQFP: 2 GLBs have 15 out of 16 I/Os bonded out.

2. 64-macrocells device, 44 TQFP: 2 GLBs have 7 out of 8 I/Os bonded out.

3. 128-macrocell device, 128 TQFP: 4 GLBs have 11 out of 12 I/Os

4. 256-macrocell device, 144 TQFP: 16 GLBs have 6 I/Os per

5. 512-macrocell device: 20 GLBs have 8 I/Os per, 12 GLBs have 4 I/Os per

ispMACH 4000Z ORP Reference Table

	4032Z	4064Z		4128Z		4256Z		
Number of I/Os	32	32	64	64	96	64	96 ¹	128
Number of GLBs	2	4	4	8	8	16	16	16
Number of I/Os / GLB	16	8	16	8	12	4	8	8
Reference ORP Table	16 I/Os / GLB	8 I/Os / GLB	16 I/Os / GLB	8 I/Os / GLB	12 I/Os / GLB	4 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB

1. 256-macrocell device, 132 csBGA: 16 GLBs have 6 I/Os per

ispMACH 4000V/B/C/Z Power Supply and NC Connections¹

Signal	44-pin TQFP ²	48-pin TQFP ²	56-ball csBGA ³	100-pin TQFP ²	128-pin TQFP ²
VCC	11, 33	12, 36	K2, A9	25, 40, 75, 90	32, 51, 96, 115
VCCO0 VCCO (Bank 0)	6	6	F3	13, 33, 95	3, 17, 30, 41, 122
VCCO1 VCCO (Bank 1)	28	30	E8	45, 63, 83	58, 67, 81, 94, 105
GND	12, 34	13, 37	H3, C8	1, 26, 51, 76	1, 33, 65, 97
GND (Bank 0)	5	5	D3	7, 18, 32, 96	10, 24, 40, 113, 123
GND (Bank 1)	27	29	G8	46, 57, 68, 82	49, 59, 74, 88, 104
NC	—	—	4032Z: A8, B10, E1, E3, F8, F10, J1, K3	—	—

1. All grounds must be electrically connected at the board level. However, for the purposes of I/O current loading, grounds are associated with the bank shown.
2. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.
3. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.

**ispMACH 4032V/B/C and 4064V/B/C Logic Signal Connections:
44-Pin TQFP**

Pin Number	Bank Number	ispMACH 4032V/B/C		ispMACH 4064V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	TDI	-	TDI	-
2	0	A5	A ⁵	A10	A ⁵
3	0	A6	A ⁶	A12	A ⁶
4	0	A7	A ⁷	A14	A ⁷
5	0	GND (Bank 0)	-	GND (Bank 0)	-
6	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
7	0	A8	A ⁸	B0	B ⁰
8	0	A9	A ⁹	B2	B ¹
9	0	A10	A ¹⁰	B4	B ²
10	-	TCK	-	TCK	-
11	-	VCC	-	VCC	-
12	-	GND	-	GND	-
13	0	A12	A ¹²	B8	B ⁴
14	0	A13	A ¹³	B10	B ⁵
15	0	A14	A ¹⁴	B12	B ⁶
16	0	A15	A ¹⁵	B14	B ⁷
17	1	CLK2/I	-	CLK2/I	-
18	1	B0	B ⁰	C0	C ⁰
19	1	B1	B ¹	C2	C ¹
20	1	B2	B ²	C4	C ²
21	1	B3	B ³	C6	C ³
22	1	B4	B ⁴	C8	C ⁴
23	-	TMS	-	TMS	-
24	1	B5	B ⁵	C10	C ⁵
25	1	B6	B ⁶	C12	C ⁶
26	1	B7	B ⁷	C14	C ⁷
27	1	GND (Bank 1)	-	GND (Bank 1)	-
28	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
29	1	B8	B ⁸	D0	D ⁰
30	1	B9	B ⁹	D2	D ¹
31	1	B10	B ¹⁰	D4	D ²
32	-	TDO	-	TDO	-
33	-	VCC	-	VCC	-
34	-	GND	-	GND	-
35	1	B12	B ¹²	D8	D ⁴
36	1	B13	B ¹³	D10	D ⁵
37	1	B14	B ¹⁴	D12	D ⁶
38	1	B15/GOE1	B ¹⁵	D14/GOE1	D ⁷
39	0	CLK0/I	-	CLK0/I	-
40	0	A0/GOE0	A ⁰	A0/GOE0	A ⁰
41	0	A1	A ¹	A2	A ¹

ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
62	1	E10	E ⁸
63	1	E12	E ⁹
64	1	E14	E ¹¹
65	1	GND	-
66	1	TMS	-
67	1	VCCO (Bank 1)	-
68	1	F0	F ⁰
69	1	F1	F ¹
70	1	F2	F ²
71	1	F4	F ³
72	1	F5	F ⁴
73	1	F6	F ⁵
74	1	GND (Bank 1)	-
75	1	F8	F ⁶
76	1	F9	F ⁷
77	1	F10	F ⁸
78	1	F12	F ⁹
79	1	F13	F ¹⁰
80	1	F14	F ¹¹
81	1	VCCO (Bank 1)	-
82	1	G14	G ¹¹
83	1	G13	G ¹⁰
84	1	G12	G ⁹
85	1	G10	G ⁸
86	1	G9	G ⁷
87	1	G8	G ⁶
88	1	GND (Bank 1)	-
89	1	G6	G ⁵
90	1	G5	G ⁴
91	1	G4	G ³
92	1	G2	G ²
93	1	G0	G ⁰
94	1	VCCO (Bank 1)	-
95	1	TDO	-
96	1	VCC	-
97	1	GND	-
98	1	H14	H ¹¹
99	1	H13	H ¹⁰
100	1	H12	H ⁹
101	1	H10	H ⁸
102	1	H9	H ⁷
103	1	H8	H ⁶
104	1	GND (Bank 1)	-

**ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections:
176-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
19	0	D4	D [^] 2	E4	E [^] 2	G4	G [^] 2
20	0	D2	D [^] 1	E2	E [^] 1	G2	G [^] 1
21	0	D0	D [^] 0	E0	E [^] 0	G0	G [^] 0
22	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
23	0	E0	E [^] 0	H0	H [^] 0	J0	J [^] 0
24	0	E2	E [^] 1	H2	H [^] 1	J2	J [^] 1
25	0	E4	E [^] 2	H4	H [^] 2	J4	J [^] 2
26	0	E6	E [^] 3	H6	H [^] 3	J6	J [^] 3
27	0	E8	E [^] 4	H8	H [^] 4	J8	J [^] 4
28	0	E10	E [^] 5	H10	H [^] 5	J10	J [^] 5
29	0	E12	E [^] 6	H12	H [^] 6	J12	J [^] 6
30	0	E14	E [^] 7	H14	H [^] 7	J14	J [^] 7
31	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
32	0	F0	F [^] 0	J0	J [^] 0	N0	N [^] 0
33	0	F2	F [^] 1	J2	J [^] 1	N2	N [^] 1
34	0	F4	F [^] 2	J4	J [^] 2	N4	N [^] 2
35	0	F6	F [^] 3	J6	J [^] 3	N6	N [^] 3
36	0	F8	F [^] 4	J8	J [^] 4	N8	N [^] 4
37	0	F10	F [^] 5	J10	J [^] 5	N10	N [^] 5
38	0	F12	F [^] 6	J12	J [^] 6	N12	N [^] 6
39	0	F14	F [^] 7	J14	J [^] 7	N14	N [^] 7
40	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
41	-	TCK	-	TCK	-	TCK	-
42	-	VCC	-	VCC	-	VCC	-
43	-	NC	-	NC	-	NC	-
44	-	NC	-	NC	-	NC	-
45	-	NC	-	NC	-	NC	-
46	-	GND	-	GND (Bank 0)	-	GND	-
47	0	G14	G [^] 7	K14	K [^] 7	O14	O [^] 7
48	0	G12	G [^] 6	K12	K [^] 6	O12	O [^] 6
49	0	G10	G [^] 5	K10	K [^] 5	O10	O [^] 5
50	0	G8	G [^] 4	K8	K [^] 4	O8	O [^] 4
51	0	G6	G [^] 3	K6	K [^] 3	O6	O [^] 3
52	0	G4	G [^] 2	K4	K [^] 2	O4	O [^] 2
53	0	G2	G [^] 1	K2	K [^] 1	O2	O [^] 1
54	0	G0	G [^] 0	K0	K [^] 0	O0	O [^] 0
55	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
56	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
57	0	H14	H [^] 7	L14	L [^] 7	P14	P [^] 7
58	0	H12	H [^] 6	L12	L [^] 6	P12	P [^] 6
59	0	H10	H [^] 5	L10	L [^] 5	P10	P [^] 5

**ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections:
176-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
101	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
102	1	L14	L ¹⁴	AX14	AX ¹⁴	GX14	GX ¹⁴
103	1	L12	L ¹²	AX12	AX ¹²	GX12	GX ¹²
104	1	L10	L ¹⁰	AX10	AX ¹⁰	GX10	GX ¹⁰
105	1	L8	L ⁸	AX8	AX ⁸	GX8	GX ⁸
106	1	L6	L ⁶	AX6	AX ⁶	GX6	GX ⁶
107	1	L4	L ⁴	AX4	AX ⁴	GX4	GX ⁴
108	1	L2	L ²	AX2	AX ²	GX2	GX ²
109	1	L0	L ⁰	AX0	AX ⁰	GX0	GX ⁰
110	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
111	1	M0	M ⁰	DX0	DX ⁰	JX0	JX ⁰
112	1	M2	M ²	DX2	DX ²	JX2	JX ²
113	1	M4	M ⁴	DX4	DX ⁴	JX4	JX ⁴
114	1	M6	M ⁶	DX6	DX ⁶	JX6	JX ⁶
115	1	M8	M ⁸	DX8	DX ⁸	JX8	JX ⁸
116	1	M10	M ¹⁰	DX10	DX ¹⁰	JX10	JX ¹⁰
117	1	M12	M ¹²	DX12	DX ¹²	JX12	JX ¹²
118	1	M14	M ¹⁴	DX14	DX ¹⁴	JX14	JX ¹⁴
119	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
120	1	N0	N ⁰	FX0	FX ⁰	NX0	NX ⁰
121	1	N2	N ²	FX2	FX ²	NX2	NX ²
122	1	N4	N ⁴	FX4	FX ⁴	NX4	NX ⁴
123	1	N6	N ⁶	FX6	FX ⁶	NX6	NX ⁶
124	1	N8	N ⁸	FX8	FX ⁸	NX8	NX ⁸
125	1	N10	N ¹⁰	FX10	FX ¹⁰	NX10	NX ¹⁰
126	1	N12	N ¹²	FX12	FX ¹²	NX12	NX ¹²
127	1	N14	N ¹⁴	FX14	FX ¹⁴	NX14	NX ¹⁴
128	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
129	-	TDO	-	TDO	-	TDO	-
130	-	VCC	-	VCC	-	VCC	-
131	-	NC	-	NC	-	NC	-
132	-	NC	-	NC	-	NC	-
133	-	NC	-	NC	-	NC	-
134	-	GND	-	GND	-	GND	-
135	1	O14	O ¹⁴	GX14	GX ¹⁴	OX14	OX ¹⁴
136	1	O12	O ¹²	GX12	GX ¹²	OX12	OX ¹²
137	1	O10	O ¹⁰	GX10	GX ¹⁰	OX10	OX ¹⁰
138	1	O8	O ⁸	GX8	GX ⁸	OX8	OX ⁸
139	1	O6	O ⁶	GX6	GX ⁶	OX6	OX ⁶
140	1	O4	O ⁴	GX4	GX ⁴	OX4	OX ⁴
141	1	O2	O ²	GX2	GX ²	OX2	OX ²

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
-	-	-	-	-	-	VCC	-	VCC	-
-	-	GND	-	GND	-	GND	-	GND	-
C3	-	TDI	-	TDI	-	TDI	-	TDI	-
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
B1	0	C14	C ⁷	C14	C ⁹	C14	C ⁷	C14	C ⁷
F5	0	C12	C ⁶	C12	C ⁸	C12	C ⁶	C12	C ⁶
D3	0	C10	C ⁵	C10	C ⁷	C10	C ⁵	C10	C ⁵
C1	0	C8	C ⁴	C9	C ⁶	C8	C ⁴	C8	C ⁴
C2	0	C6	C ³	C8	C ⁵	C6	C ³	C6	C ³
E3	0	C4	C ²	C6	C ⁴	C4	C ²	C4	C ²
D2	0	C2	C ¹	C4	C ³	C2	C ¹	C2	C ¹
F6	0	C0	C ⁰	C2	C ²	C0	C ⁰	C0	C ⁰
D1	0	NC	-	C1	C ¹	F6	F ³	H0	H ⁰
E2	0	NC	-	C0	C ⁰	F4	F ²	H4	H ¹
E4	0	NC	-	NC	-	D6	D ³	F4	F ²
G5	0	NC	-	NC	-	D4	D ²	F6	F ³
E1	0	NC	-	NC	-	NC	-	F8	F ⁴
-	0	-	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
F2	0	NC	-	NC	-	NC	-	F10	F ⁵
F1	0	NC	-	NC	-	D2	D ¹	F12	F ⁶
G1	0	NC	-	NC	-	D0	D ⁰	F14	F ⁷
G6	0	NC	-	D14	D ⁹	F2	F ¹	H8	H ²
G4	0	NC	-	D12	D ⁸	F0	F ⁰	H12	H ³
H6	0	D14	D ⁷	D10	D ⁷	E14	E ⁷	G14	G ⁷
G3	0	D12	D ⁶	D9	D ⁶	E12	E ⁶	G12	G ⁶
H5	0	D10	D ⁵	D8	D ⁵	E10	E ⁵	G10	G ⁵
G2	0	D8	D ⁴	D6	D ⁴	E8	E ⁴	G8	G ⁴
H1	0	D6	D ³	D4	D ³	E6	E ³	G6	G ³
H2	0	D4	D ²	D2	D ²	E4	E ²	G4	G ²
H3	0	D2	D ¹	D1	D ¹	E2	E ¹	G2	G ¹
H4	0	D0	D ⁰	D0	D ⁰	E0	E ⁰	G0	G ⁰
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	-	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
J4	0	E0	E ⁰	E0	E ⁰	H0	H ⁰	J0	J ⁰
J3	0	E2	E ¹	E1	E ¹	H2	H ¹	J2	J ¹
J2	0	E4	E ²	E2	E ²	H4	H ²	J4	J ²
J1	0	E6	E ³	E4	E ³	H6	H ³	J6	J ³
K1	0	E8	E ⁴	E6	E ⁴	H8	H ⁴	J8	J ⁴
J5	0	E10	E ⁵	E8	E ⁵	H10	H ⁵	J10	J ⁵
K2	0	E12	E ⁶	E9	E ⁶	H12	H ⁶	J12	J ⁶

ispMACH 4000C (1.8V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4128C	LC4128C-27T128C	128	1.8	2.7	TQFP	128	92	C
	LC4128C-5T128C	128	1.8	5	TQFP	128	92	C
	LC4128C-75T128C	128	1.8	7.5	TQFP	128	92	C
	LC4128C-27T100C	128	1.8	2.7	TQFP	100	64	C
	LC4128C-5T100C	128	1.8	5	TQFP	100	64	C
	LC4128C-75T100C	128	1.8	7.5	TQFP	100	64	C
LC4256C	LC4256C-3FT256AC	256	1.8	3	ftBGA	256	128	C
	LC4256C-5FT256AC	256	1.8	5	ftBGA	256	128	C
	LC4256C-75FT256AC	256	1.8	7.5	ftBGA	256	128	C
	LC4256C-3FT256BC	256	1.8	3	ftBGA	256	160	C
	LC4256C-5FT256BC	256	1.8	5	ftBGA	256	160	C
	LC4256C-75FT256BC	256	1.8	7.5	ftBGA	256	160	C
	LC4256C-3F256AC ¹	256	1.8	3	fpBGA	256	128	C
	LC4256C-5F256AC ¹	256	1.8	5	fpBGA	256	128	C
	LC4256C-75F256AC ¹	256	1.8	7.5	fpBGA	256	128	C
	LC4256C-3F256BC ¹	256	1.8	3	fpBGA	256	160	C
	LC4256C-5F256BC ¹	256	1.8	5	fpBGA	256	160	C
	LC4256C-75F256BC ¹	256	1.8	7.5	fpBGA	256	160	C
	LC4256C-3T176C	256	1.8	3	TQFP	176	128	C
	LC4256C-5T176C	256	1.8	5	TQFP	176	128	C
	LC4256C-75T176C	256	1.8	7.5	TQFP	176	128	C
	LC4256C-3T100C	256	1.8	3	TQFP	100	64	C
	LC4256C-5T100C	256	1.8	5	TQFP	100	64	C
	LC4256C-75T100C	256	1.8	7.5	TQFP	100	64	C
LC4384C	LC4384C-35FT256C	384	1.8	3.5	ftBGA	256	192	C
	LC4384C-5FT256C	384	1.8	5	ftBGA	256	192	C
	LC4384C-75FT256C	384	1.8	7.5	ftBGA	256	192	C
	LC4384C-35F256C ¹	384	1.8	3.5	fpBGA	256	192	C
	LC4384C-5F256C ¹	384	1.8	5	fpBGA	256	192	C
	LC4384C-75F256C ¹	384	1.8	7.5	fpBGA	256	192	C
	LC4384C-35T176C	384	1.8	3.5	TQFP	176	128	C
	LC4384C-5T176C	384	1.8	5	TQFP	176	128	C
	LC4384C-75T176C	384	1.8	7.5	TQFP	176	128	C
LC4512C	LC4512C-35FT256C	512	1.8	3.5	ftBGA	256	208	C
	LC4512C-5FT256C	512	1.8	5	ftBGA	256	208	C
	LC4512C-75FT256C	512	1.8	7.5	ftBGA	256	208	C
	LC4512C-35F256C ¹	512	1.8	3.5	fpBGA	256	208	C
	LC4512C-5F256C ¹	512	1.8	5	fpBGA	256	208	C
	LC4512C-75F256C ¹	512	1.8	7.5	fpBGA	256	208	C
	LC4512C-35T176C	512	1.8	3.5	TQFP	176	128	C
	LC4512C-5T176C	512	1.8	5	TQFP	176	128	C
	LC4512C-75T176C	512	1.8	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000B (2.5V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032B	LC4032B-5T48I	32	2.5	5	TQFP	48	32	I
	LC4032B-75T48I	32	2.5	7.5	TQFP	48	32	I
	LC4032B-10T48I	32	2.5	10	TQFP	48	32	I
	LC4032B-5T44I	32	2.5	5	TQFP	44	30	I
	LC4032B-75T44I	32	2.5	7.5	TQFP	44	30	I
	LC4032B-10T44I	32	2.5	10	TQFP	44	30	I
LC4064B	LC4064B-5T100I	64	2.5	5	TQFP	100	64	I
	LC4064B-75T100I	64	2.5	7.5	TQFP	100	64	I
	LC4064B-10T100I	64	2.5	10	TQFP	100	64	I
	LC4064B-5T48I	64	2.5	5	TQFP	48	32	I
	LC4064B-75T48I	64	2.5	7.5	TQFP	48	32	I
	LC4064B-10T48I	64	2.5	10	TQFP	48	32	I
	LC4064B-5T44I	64	2.5	5	TQFP	44	30	I
	LC4064B-75T44I	64	2.5	7.5	TQFP	44	30	I
	LC4064B-10T44I	64	2.5	10	TQFP	44	30	I
LC4128B	LC4128B-5T128I	128	2.5	5	TQFP	128	92	I
	LC4128B-75T128I	128	2.5	7.5	TQFP	128	92	I
	LC4128B-10T128I	128	2.5	10	TQFP	128	92	I
	LC4128B-5T100I	128	2.5	5	TQFP	100	64	I
	LC4128B-75T100I	128	2.5	7.5	TQFP	100	64	I
	LC4128B-10T100I	128	2.5	10	TQFP	100	64	I
LC4256B	LC4256B-5FT256AI	256	2.5	5	ftBGA	256	128	I
	LC4256B-75FT256AI	256	2.5	7.5	ftBGA	256	128	I
	LC4256B-10FT256AI	256	2.5	10	ftBGA	256	128	I
	LC4256B-5FT256BI	256	2.5	5	ftBGA	256	160	I
	LC4256B-75FT256BI	256	2.5	7.5	ftBGA	256	160	I
	LC4256B-10FT256BI	256	2.5	10	ftBGA	256	160	I
	LC4256B-5F256AI ¹	256	2.5	5	fpBGA	256	128	I
	LC4256B-75F256AI ¹	256	2.5	7.5	fpBGA	256	128	I
	LC4256B-10F256AI ¹	256	2.5	10	fpBGA	256	128	I
	LC4256B-5F256BI ¹	256	2.5	5	fpBGA	256	160	I
	LC4256B-75F256BI ¹	256	2.5	7.5	fpBGA	256	160	I
	LC4256B-10F256BI ¹	256	2.5	10	fpBGA	256	160	I
	LC4256B-5T176I	256	2.5	5	TQFP	176	128	I
	LC4256B-75T176I	256	2.5	7.5	TQFP	176	128	I
	LC4256B-10T176I	256	2.5	10	TQFP	176	128	I
	LC4256B-5T100I	256	2.5	5	TQFP	100	64	I
	LC4256B-75T100I	256	2.5	7.5	TQFP	100	64	I
	LC4256B-10T100I	256	2.5	10	TQFP	100	64	I

ispMACH 4000B (2.5V) Lead-Free Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4128B	LC4128B-5TN128I	128	2.5	5	Lead-Free TQFP	128	92	I
	LC4128B-75TN128I	128	2.5	7.5	Lead-Free TQFP	128	92	I
	LC4128B-10TN128I	128	2.5	10	Lead-Free TQFP	128	92	I
	LC4128B-5TN100I	128	2.5	5	Lead-Free TQFP	100	64	I
	LC4128B-75TN100I	128	2.5	7.5	Lead-Free TQFP	100	64	I
	LC4128B-10TN100I	128	2.5	10	Lead-Free TQFP	100	64	I
LC4256B	LC4256B-5FTN256AI	256	2.5	5	Lead-Free ftBGA	256	128	I
	LC4256B-75FTN256AI	256	2.5	7.5	Lead-Free ftBGA	256	128	I
	LC4256B-10FTN256AI	256	2.5	10	Lead-Free ftBGA	256	128	I
	LC4256B-5FTN256BI	256	2.5	5	Lead-Free ftBGA	256	160	I
	LC4256B-75FTN256BI	256	2.5	7.5	Lead-Free ftBGA	256	160	I
	LC4256B-10FTN256BI	256	2.5	10	Lead-Free ftBGA	256	160	I
	LC4256B-5FN256AI ¹	256	2.5	5	Lead-Free fpBGA	256	128	I
	LC4256B-75FN256AI ¹	256	2.5	7.5	Lead-Free fpBGA	256	128	I
	LC4256B-10FN256AI ¹	256	2.5	10	Lead-Free fpBGA	256	128	I
	LC4256B-5FN256BI ¹	256	2.5	5	Lead-Free fpBGA	256	160	I
	LC4256B-75FN256BI ¹	256	2.5	7.5	Lead-Free fpBGA	256	160	I
	LC4256B-10FN256BI ¹	256	2.5	10	Lead-Free fpBGA	256	160	I
	LC4256B-5TN176I	256	2.5	5	Lead-Free TQFP	176	128	I
	LC4256B-75TN176I	256	2.5	7.5	Lead-Free TQFP	176	128	I
	LC4256B-10TN176I	256	2.5	10	Lead-Free TQFP	176	128	I
	LC4256B-5TN100I	256	2.5	5	Lead-Free TQFP	100	64	I
	LC4256B-75TN100I	256	2.5	7.5	Lead-Free TQFP	100	64	I
	LC4256B-10TN100I	256	2.5	10	Lead-Free TQFP	100	64	I
LC4384B	LC4384B-5FTN256I	384	2.5	5	Lead-Free ftBGA	256	192	I
	LC4384B-75FTN256I	384	2.5	7.5	Lead-Free ftBGA	256	192	I
	LC4384B-10FTN256I	384	2.5	10	Lead-Free ftBGA	256	192	I
	LC4384B-5FN256I ¹	384	2.5	5	Lead-Free fpBGA	256	192	I
	LC4384B-75FN256I ¹	384	2.5	7.5	Lead-Free fpBGA	256	192	I
	LC4384B-10FN256I ¹	384	2.5	10	Lead-Free fpBGA	256	192	I
	LC4384B-5TN176I	384	2.5	5	Lead-Free TQFP	176	128	I
	LC4384B-75TN176I	384	2.5	7.5	Lead-Free TQFP	176	128	I
	LC4384B-10TN176I	384	2.5	10	Lead-Free TQFP	176	128	I
LC4512B	LC4512B-5FTN256I	512	2.5	5	Lead-Free ftBGA	256	208	I
	LC4512B-75FTN256I	512	2.5	7.5	Lead-Free ftBGA	256	208	I
	LC4512B-10FTN256I	512	2.5	10	Lead-Free ftBGA	256	208	I
	LC4512B-5FN256I ¹	512	2.5	5	Lead-Free fpBGA	256	208	I
	LC4512B-75FN256I ¹	512	2.5	7.5	Lead-Free fpBGA	256	208	I
	LC4512B-10FN256I ¹	512	2.5	10	Lead-Free fpBGA	256	208	I
	LC4512B-5TN176I	512	2.5	5	Lead-Free TQFP	176	128	I
	LC4512B-75TN176I	512	2.5	7.5	Lead-Free TQFP	176	128	I
	LC4512B-10TN176I	512	2.5	10	Lead-Free TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Lead-Free Extended Temperature Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-75TN48E	32	3.3	7.5	Lead-free TQFP	48	32	E
	LC4032V-75TN44E	32	3.3	7.5	Lead-free TQFP	44	30	E
LC4064V	LC4064V-75TN100E	64	3.3	7.5	Lead-free TQFP	100	64	E
	LC4064V-75TN48E	64	3.3	7.5	Lead-free TQFP	48	32	E
	LC4064V-75TN44E	64	3.3	7.5	Lead-free TQFP	44	30	E
LC4128V	LC4128V-75TN144E	128	3.3	7.5	Lead-free TQFP	144	96	E
	LC4128V-75TN128E	128	3.3	7.5	Lead-free TQFP	128	92	E
	LC4128V-75TN100E	128	3.3	7.5	Lead-free TQFP	100	64	E
LC4256V	LC4256V-75TN176E	256	3.3	7.5	Lead-free TQFP	176	128	E
	LC4256V-75TN144E	256	3.3	7.5	Lead-free TQFP	144	96	E
	LC4256V-75TN100E	256	3.3	7.5	Lead-free TQFP	100	64	E

For Further Information

In addition to this data sheet, the following technical notes may be helpful when designing with the ispMACH 4000V/B/C/Z family:

- TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#)
- TN1005, [Power Estimation in ispMACH 4000V/B/C/Z Devices](#)

Revision History

Date	Version	Change Summary
—	—	Previous Lattice releases.
July 2003	17z	Changed device status for LC4064ZC and LC4128ZC to production release and updated/added AC and DC parameters as well as ordering part numbers for LC4064ZC and LC4128ZC devices.
		Improved leakage current specifications for ispMACH 4000Z. For ispMACH 4000V/B/C IIL, IIH condition now includes 0V and 3.6V end points ($0 \leq V_{IN} \leq 3.6V$).
		Added 132-ball chip scale BGA power supply and NC connections.
		Added 132-ball chip scale BGA logic signal connections for LC4064ZC, LC4128ZC and LC4256ZC devices.
		Added lead-free package designators.
October 2003	18z	Hot socketing characteristics footnote 1. has been enhanced; Insensitive to sequence of VCC or VCCO. However, assumes monotonic rise/fall rates for Vcc and Vcco, provided $(V_{IN} - V_{CCO}) \leq 3.6V$.
		Improved LC4064ZC t _S to 2.5ns, t _{ST} to 2.7ns and f _{MAX} (Ext.) to 175MHz, LC4128ZC t _{CO} to 3.5ns and f _{MAX} (Ext.) to 161MHz (version v.2.1).
		Improved associated internal timing numbers and timing adders (version v.2.1).
		Added ispMACH 4000V/B/C/Z ORP Reference Tables.
		Enhanced ORP information in device pinout tables consistent with the ORP Combinations for I/O Blocks tables (table 6, 7, 8 and 9 in page 9-11).
		Corrected GLB/MC/Pad information in the 256-fpBGA pinouts for the LC4256V/B/C 160-I/O version.
		Added the ispMACH 4000 Family Speed Grade Offering table.
		Added the ispMACH 4128ZC Industrial and Automotive Device OPNs
December 2003	19z	Added the ispMACH 4032ZC and 4064ZC Industrial and Automotive Device OPNs